



PCIe Application Acceleration

Fusion ioMemory™-PX600

Highest Transaction Rate/GB | Optimized for Mixed Workloads | Proven Flash Memory

Model Number	PX600-1000	PX600-1300	PX600-2600	PX600-5200
Usable Capacity	1,000 GB	1,300 GB	2,600 GB	5,200 GB
NAND Type	MLC (Multi Level Cell)	MLC (Multi Level Cell)	MLC (Multi Level Cell)	MLC (Multi Level Cell)
Read Bandwidth (GB/s)	2.7	2.7	2.7	2.7
Write Bandwidth (GB/s)	1.5	1.7*	2.2*	2.1*
Ran. Read IOPS (4K)	196,000	235,000	350,000	285,000
Ran. Write IOPS (4K)	330,000	375,000	385,000	385,000
Read Access Latency	92µs	92µs	92µs	92µs
Write Access Latency	15µs	15µs	15µs	15µs
Bus Interface	PCI-Express 2.0 x8			
Endurance (PBW)	12	16	32	64
Weight	5.2 ounces			7.25 ounces
Form Factor	Low Profile			Standard Height, Half-Length
Warranty	5 years or maximum endurance used			
Operating Systems	Microsoft Windows: Windows Server 2012 R2, Windows Server 2012, Windows 2008 R2 SP1 Linux: RHEL 5/6; SLES 11; OEL 5/6; CentOS 5/6; Debian Squeeze; Ubuntu 12/13 UNIX: Solaris 11.1/11 x64; Solaris 10 U11 x64 Hypervisors: VMware ESXi 5.0/5.1/5.5, Windows Server 2012 with Hyper-V, Windows Server 2012 R2 with Hyper-V			

*Write BW achieved with optional high power mode. Maximum Write bandwidth performance of 1.6 GB/s achievable within 25 W power limit

Agency

US/Canada	FCC Title 47, Part 15 Subpart B, Class A, CAN ICES-3 (A) NMB-3 (A)
Europe/CE	EN 55022: 2010, EN 61000-3-2: 2006 plus A1:2009 & A2:2009, EN 61000-3-3: 2008, EN 55024: 2010
Japan/VCCI	VCCI V-3/2013.04 Class A & EN 55022 (2010) Class A, ANSI C63.4: 2009
Taiwan	BSMI CNS 13438: 2006 Class A, EN 55022 (2006)A1 (2007) Class A
Australia/New Zealand	AS/NZS CISPR 22: 2009 plus A1:2010
Korea	MSIP-REM-FIO-ioMemoryPX600
Low Voltage Directive Testing	Directive: 2006/95/EC, EN 60950-1:2006 + A11:2009 + A1:2010 + A12:2011 and IEC 60950-1:2005 + A1:2009
RoHS	DIRECTIVE 2011/65/EU
REACH	Regulation (EC) No 1907/2006
WEEE	Directive 2002/96/EC

Environmental Specifications

	Min	Max
Temperature¹	Operational	55°C
	Non-operational	70°C
Power Requirements	25 W	
Air Flow (LFM)²	300	
Humidity (%)	Non-condensing	5
	Operational	95
Altitude (ft)	Operational	10,000
	Non-operational	30,000

Specifications subject to change without notice.

¹ Temperature derated 1°C per 1000 ft elevation above sea level

² Fusion ioMemory is designed for server platforms only and relies on 300 LFM (min) airflow, which is required for normal operation in server environments.

Contact information

fusion-sales@sandisk.com

SanDisk

951 SanDisk Drive
Milpitas, CA 95035-7933, USA
T: 1-800-578-6007

For more information, please visit:

www.sandisk.com/fusion

SanDisk®

At SanDisk, we're expanding the possibilities of data storage. For more than 25 years, SanDisk's ideas have helped transform the industry, delivering next generation storage solutions for consumers and businesses around the globe.

951 SanDisk Drive | Milpitas | CA 95035 | USA

©2014 SanDisk Corporation. All rights reserved. SanDisk is a trademark of SanDisk Corporation, registered in the United States and other Countries. Fusion ioMemory and others are trademarks of SanDisk Enterprise IP LLC.